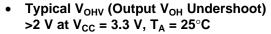
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DUAL 2-INPUT POSITIVE-AND GATE

FEATURES

- **Qualified for Automotive Applications**
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 4.7 ns at 3.3 V
- Low Power Consumption, 10-μA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$



- Ioff Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **ESD Protection Exceeds JESD 22**

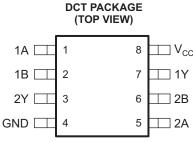
DCU PACKAGE

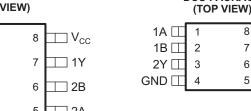
- 2000-V Human-Body Model (A114-A)
- 1000-V Charged-Device Model (C101)

oxdot $V_{
m cc}$

□ 2B

6 5





See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

This dual 2-input positive-AND gate is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC2G08 performs the Boolean function $Y = A \bullet B$ or $Y = \overline{A} + \overline{B}$ in positive logic.

This device is fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION(1)

T _A	PACKA	3E ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽³⁾
–40°C to 85°C	SSOP - DCT	Tape and reel	SN74LVC2G08IDCTRQ1	C08
-40 C to 65 C	VSSOP - DCU	Tape and reel	SN74LVC2G08IDCURQ1 (4)	C08_

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

Product preview



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

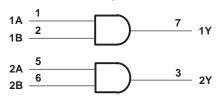
DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site. DCU: The actual top-side marking has one additional character that designates the wafer fab/assembly site.



FUNCTION TABLE (EACH GATE)

INP	JTS	OUTPUT
Α	В	Y
Н	Н	Н
L	X	L
X	L	L

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	6.5	V
V_{I}	Input voltage range (2)		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-imp	-0.5	6.5	V	
Vo	Voltage range applied to any output in the high or le	-0.5	V _{CC} + 0.5	V	
I _{IK}	Input clamp current	V _I < 0		- 50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through V _{CC} or GND			±100	mA
0	Decline the model in the decore (4)	DCT package		220	00/11/
θ_{JA}	Package thermal impedance (4)	DCU package		227	°C/W
T _{stg}	Storage temperature range	-65	150	°C	

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

⁽²⁾ The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

³⁾ The value of V_{CC} is provided in the recommended operating conditions table.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V	Complement	Operating	1.65	5.5	V
V _{CC}	Supply voltage	Data retention only	1.5		V
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		
.,	High level inner college	V _{CC} = 2.3 V to 2.7 V	1.7		V
V_{IH}	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2		V
		V _{CC} = 4.5 V to 5.5 V	$0.7 \times V_{CC}$		
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
V	Low level input valtage	V _{CC} = 2.3 V to 2.7 V		0.7	V
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		0.8	V
		V _{CC} = 4.5 V to 5.5 V		$0.3 \times V_{CC}$	
VI	Input voltage	,	0	5.5	V
Vo	Output voltage		0	V _{CC}	V
		V _{CC} = 1.65 V		-4	
		V _{CC} = 2.3 V		-8	
I_{OH}	High-level output current	V 2V		-16	mA
		V _{CC} = 3 V		-24	
		V _{CC} = 4.5 V		-32	
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		8	
I_{OL}	Low-level output current	V 0V		16	mA
		V _{CC} = 3 V		24	
		V _{CC} = 4.5 V		32	
		$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}, 2.5 \text{ V} \pm 0.2 \text{ V}$		20	
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V
		$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$			
T _A	Operating free-air temperature	,	-40	85	°C

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN TYP ⁽¹⁾ MAX	UNIT
	$I_{OH} = -100 \mu A$	1.65 V to 5.5 V	V _{CC} – 0.1	
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2	
V	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9	V
V _{OH}	$I_{OH} = -16 \text{ mA}$	3 V	2.4	V
	$I_{OH} = -24 \text{ mA}$	3 V	2.3	
	$I_{OH} = -32 \text{ mA}$	4.5 V	3.8	
	I _{OL} = 100 μA	1.65 V to 5.5 V	0.1	
	I _{OL} = 4 mA	1.65 V	0.45	
V	I _{OL} = 8 mA	2.3 V	0.3	V
V _{OL}	I _{OL} = 16 mA	3 V	0.4	V
	I _{OL} = 24 mA	3 V	0.55	
	I _{OL} = 32 mA	4.5 V	0.55	
I _I A or B inputs	V _I = 5.5 V or GND	0 to 5.5 V	±5	μΑ
I _{off}	V_1 or $V_0 = 5.5 \text{ V}$	0	±10	μΑ
I _{CC}	$V_1 = 5.5 \text{ V or GND}, \qquad I_0 = 0$	1.65 V to 5.5 V	10	μΑ
ΔI_{CC}	One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 5.5 V	500	μΑ
C _I	$V_I = V_{CC}$ or GND	3.3 V	5	pF

⁽¹⁾ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} = : ± 0.2		V _{CC} = ± 0.3		V _{CC} = ± 0.5		UNIT
		(001P01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Υ	2.6	9	1	5.1	1	4.7	1	3.8	ns

Operating Characteristics

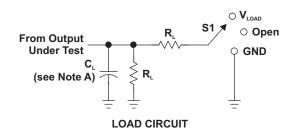
 $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	V _{CC} = 5 V	UNIT	
PARAMETER		TYP		TYP	TYP	TYP	UNII	
C_{pd}	Power dissipation capacitance	f = 10 MHz	17	17	17	20	pF	

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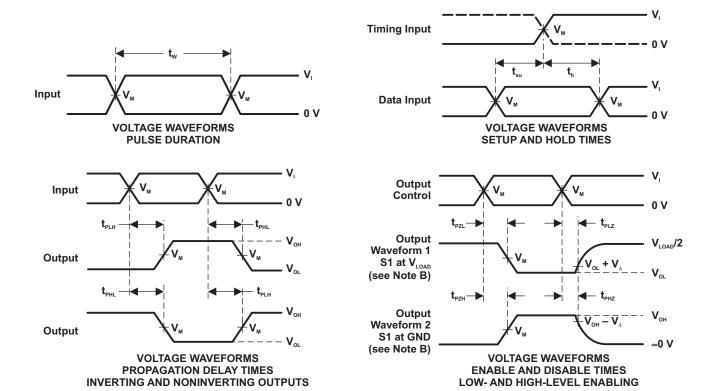


PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	\mathbf{V}_{LOAD}
t _{PHZ} /t _{PZH}	GND

	INI	PUTS		v			.,
V _{cc}	V,	t,/t,	V _M	V _{LOAD}	C _L	R _⊾	V _A
1.8 V ± 0.15 V	V _{cc}	≤2 ns	V _{cc} /2	2 × V _{cc}	30 pF	1 k Ω	0.15 V
2.5 V ± 0.2 V	V _{cc}	≤2 ns	V _{cc} /2	2 × V _{cc}	30 pF	500 Ω	0.15 V
3.3 V ± 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V ± 0.5 V	V _{cc}	≤2.5 ns	V _{cc} /2	2 × V _{cc}	50 pF	500 Ω	0.3 V



NOTES: A. C, includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{o} = 50 Ω .
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and \dot{t}_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. $t_{\mbox{\tiny PLH}}$ and $t_{\mbox{\tiny PHL}}$ are the same as $t_{\mbox{\tiny pd}}.$
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins Pa	ackage Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC2G08IDCTRQ1	ACTIVE	SM8	DCT	8	3000	TBD	CU	Level-1-220C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LVC2G08-Q1:

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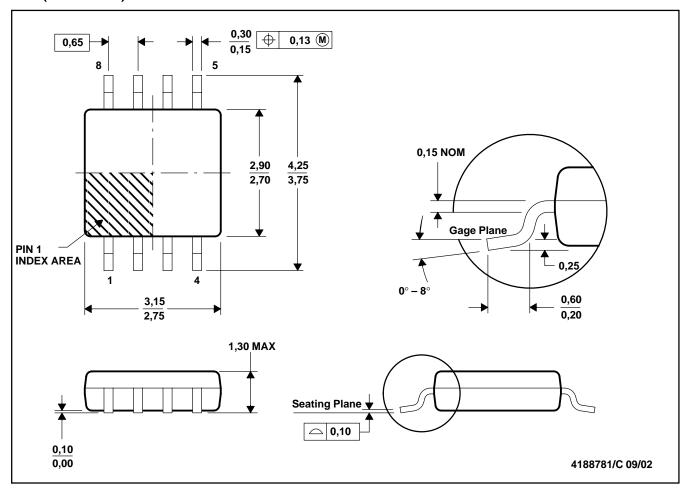
Enhanced Product: SN74LVC2G08-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

DCT (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion
- D. Falls within JEDEC MO-187 variation DA.

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